

Title (en)
MOULDED ELECTROTECHNICAL PROTECTION COMPONENT

Title (de)
GEFORMTES ELEKTROTECHNISCHES SCHUTZELEMENT

Title (fr)
COMPOSANT MOULÉ POUR PROTECTION ÉLECTROTECHNIQUE

Publication
EP 2727123 A2 20140507 (EN)

Application
EP 12819868 A 20120629

Priority
• NO 20110940 A 20110629
• NO 2012050127 W 20120629

Abstract (en)
[origin: WO2013019118A2] Molded electrical protection component with encapsulation devices suited to protect the component against ingress of solid objects and fluids, where the encapsulation devices comprise molding compound that surround parts of the component in order to contribute to achieve an improved degree of encapsulation, and where the molded component further comprises safety devices for handling of ionized gas formed in the case of short circuit currents in the protection component, and a corresponding method.

IPC 8 full level
H01H 9/04 (2006.01)

CPC (source: EP)
H01H 9/043 (2013.01); **H01H 2009/048** (2013.01)

Citation (search report)
See references of WO 2013019118A2

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2013019118 A2 20130207; WO 2013019118 A3 20130801; DK 2727123 T3 20151026; EP 2727123 A2 20140507;
EP 2727123 B1 20150812; NO 20110940 A1 20121231; NO 334147 B1 20131216

DOCDB simple family (application)
NO 2012050127 W 20120629; DK 12819868 T 20120629; EP 12819868 A 20120629; NO 20110940 A 20110629